



## Material Content Data Sheet



<b>Sales Product Name</b>		BAS 40-05W H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000845510						
<b>Package</b>		PG-SOT323-3-1		<b>Weight*</b>		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		10	
	noble metal	gold	7440-57-5	0.006	0.10		1005	
	inorganic material	silicon	7440-21-3	0.051	0.86	0.96	8579	9594
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1322	
	non noble metal	copper	7440-50-8	2.617	43.89	44.07	438936	440787
wire	non noble metal	copper	7440-50-8	0.005	0.08	0.08	776	776
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5249	
	plastics	epoxy resin	-	0.673	11.29		112855	
	inorganic material	silicondioxide	60676-86-0	2.425	40.68	52.49	406802	524906
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22258	22258
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1679	1679
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com